

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJQ14SN06
Package Type :	SOP8

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	1.96%
Lead Frame	Cu	7440-50-8	97.43%	40.06%
	Fe	7439-89-6	2.30%	
	P	7723-14-0	0.10%	
	Zn	7440-66-6	0.15%	
	Pb	7439-92-1	0.01%	
	Silver	7440-22-4	0.01%	
Die Attach	Silver Powder	7440-22-4	70-90%	0.59%
	Epoxy Resin	9003-36-5	5-10%	
	Diluent A	3101-60-8	1-5%	
	Diluent B	Trade Secret	1-5%	
	Diluent C	Trade Secret	1-5%	
	Hardener A	Trade Secret	1-5%	
	Hardener B	Trade Secret	1-5%	
	Solvent	Trade Secret	0.1-1%	
	Organic Peroide	Trade Secret	0.1-1%	
Wire	Cu	7440-50-8	100.00%	0.50%
Compound	Epoxy Resin 1	Trade secret	0.5~8%	55.93%
	Epoxy Resin 2	Trade secret	0~6%	
	Phenol Resin	Trade secret	3~8%	
	Organic Phosphorus compounds	Trade secret	<1%	
	Carbon black	1333-86-4	<0.3%	
	Amorphous silica1	60676-86-0	67~92%	
	Amorphous silica2	7631-86-9	0~15%	
Plating	Tin	7440-31-5	100.00%	0.96%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.